

S/N 10/722,838

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Suan J. Boon	Examiner:	James M. Mitchell
Serial No.:	10/722,838	Group Art Unit:	2813
Filed:	November 26, 2003	Docket No.:	303.601US3
Title:	METHOD OF PACKAGING AT A WAFER LEVEL		

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

This responds to the Office Action mailed on April 6, 2007. Please amend the above-identified patent application as follows.